

Features

· Choice of various viewing angles

Available on tape and reel

· Reliable and robust

· Lead Free

Specifications

Dice material : GaAsP / GaAsP Emmiting Colour : Red / Green Lens colour : White Diffused

Dominant wavelength : 630nm / 575nm Luminous intensity (IV) : 10mcd / 14mcd

RoHS Compliant

Applications

- TV set
- Monitor
- · Telephone
- Computer

Selection Guide

Part Number	Dice	Lens Type	Luminou	Viewing Angle		
			Min	Тур	Max	201/2
MP008274	(R)GaAsP	White Diffused	4	10	-	60
WP006274	(B)GaAsP White Dillused	6	14	-	60	

Note:

- 1. 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
- 2. The above luminous intensity measurement allowance tolerance ±15%

Electrical and Optical Characteristics at Ta=25°C

Parameter	Device	Min.	Тур	Max	Units	Test conditions
Forward voltage	R	1.7	2	2.4	V	IF=20mA
Forward voltage	G	1.7	2	2.4		
Reverse Current	IR	-	-	10	uA	VR=5V
Deminant wavelength	R	620	-	630	nm	IF=20mA
Dominant wavelength	G	565	-	575		

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	R	60	mW
DC Forward Current	IF	30	mA
Peak Forward Current [1]	IFP	60	
Reverse Voltage	VR	5	V
Electrostatic Discharge (HBM)	ESD	2000	V
Operating Temperature	Topr	-40 to +85	°C
Storage Temperature	Tstg	-40 to +100	
Lead Soldering Temperature [1.6mm(.063") From Body]		260°C for 5 seconds	

Notes:

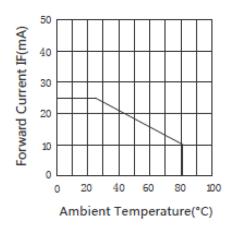
- 1. 1/10 Duty cycle,0.1ms pulse width.
- 2. Measurement Errors:Forward Voltage:±0.1V,Luminous Intensity:±10%mcd,Wavelength(x,y)±1nm/±0.01

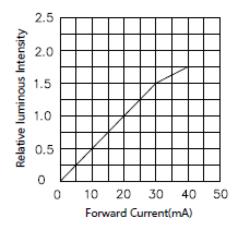


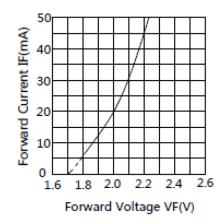
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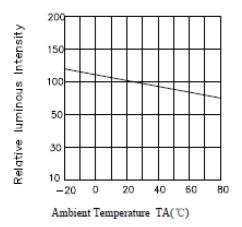
Typical optical characteristics curves

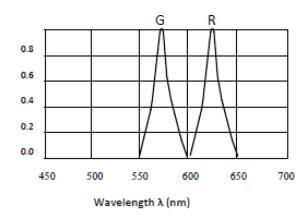
Ambient Temperature VS. Forward Current

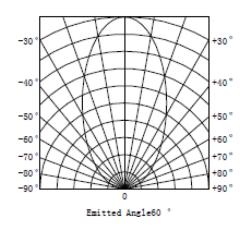








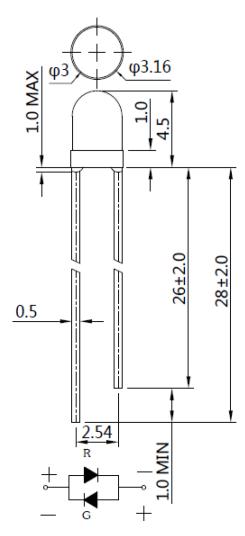






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Dimensions



Tolerance is ±0.25mm unless otherwise noted.

Dimensions: Millimetres

1. Soldering

- · When soldering leave a minimum of 2mm clearance from the base of the lens to the soldering point.
- · Dipping the lens into the solder must be avoided.
- Do not apply any external stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering conditions:

Solderi	ng iron	Wave soldering		
Temperature	320°C Max	Pre-heat Pre-heat time	120°C Max 120 sec.Max	
Soldering time	3 sec.Max (one time only)	Solder wave Soldering time	260°C Max 5 sec.Max	

Note: Excessive soldering temperature and/or time might result in deformation of the LED lens or catastrophic failure of the LED.



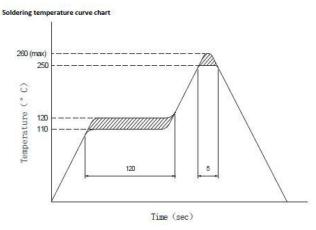


2. Drive Method

An LED is a current-operated device, In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.



- (A) Recommended circuit
- (B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.



NOTES

After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature. A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.

Part Number Table

Description	Part Number
Round LED, Red/Geen, 630/575nm, 60°, 10/14mcd, Through hole	MP008274

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